



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

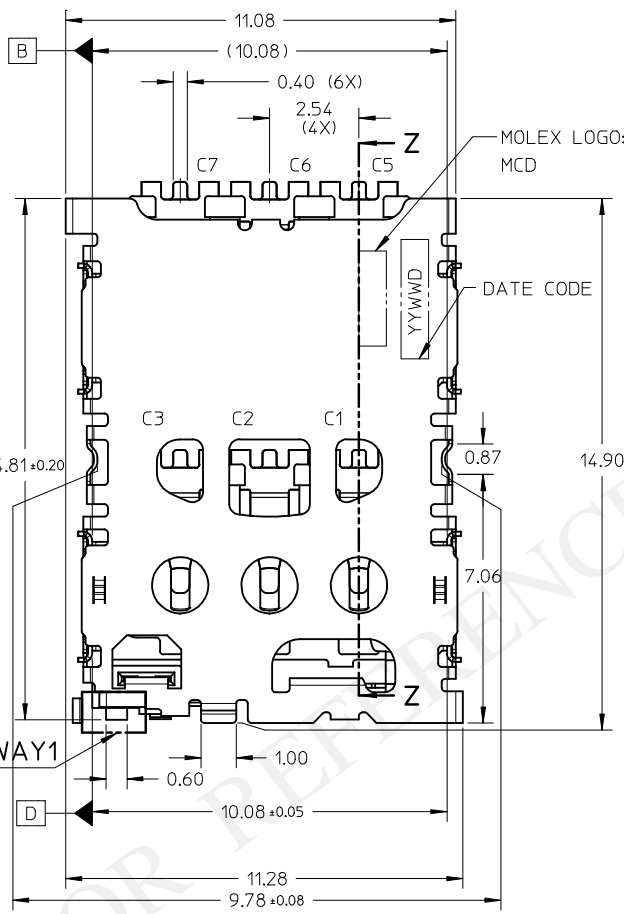
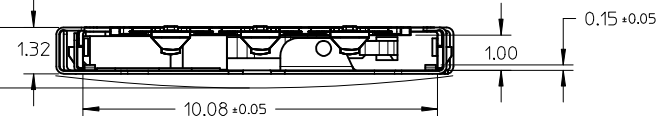
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

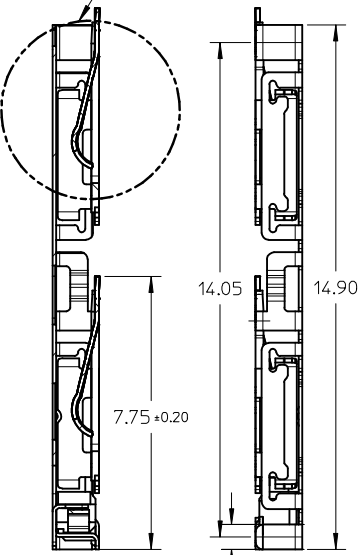


10 9 8 7 6 5 4 3 2 1

△ (1.50 MAX)
(WITH MAXIMUM CARD)

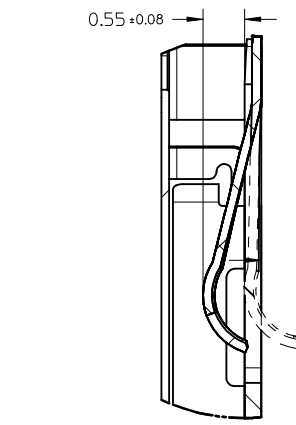


DETAIL 1



SECTION Z-Z

CUTAWAY 1



DETAIL 1

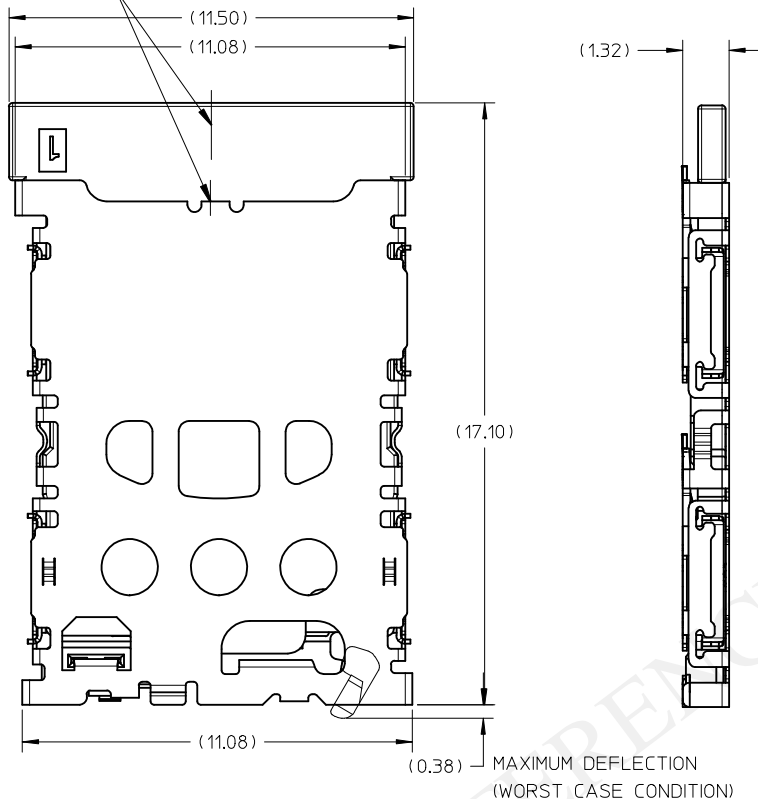
NOTES:

1. MATERIALS:
 - 1.1 CONNECTOR:-
 - INSERT MOLD HOUSING: LCP, GLASS FILLED, UL94V-0, COLOUR BLACK.
 - TERMINAL: TITANIUM COPPER, THICKNESS: 0.12MM
 - DETECT PIN: TITANIUM COPPER, THICKNESS: 0.12MM
 - SHELL: STAINLESS STEEL, THICKNESS: 0.10MM
 - 2. PLATING FINISHES:
 - 2.1 TERMINAL:-
 - CONTACT: 0.38um MIN. GOLD ON CONTACT AREA OVER 2.00um MIN. NICKEL UNDERPLATE.
 - SOLDERTAIL: 0.025um MIN. GOLD FLASH OVER 2.00um MIN. NICKEL UNDERPLATE.
 - 2.2 SHELL:-
 - CONTACT: 0.05um MIN. GOLD ON CONTACT AREA OVER 2.00um MIN. NICKEL UNDERPLATE.
 - SOLDERTAIL: 0.025um MIN. GOLD FLASH OVER 2.00um MIN. NICKEL UNDERPLATE.
 - 2.3 DETECT PIN:-
 - CONTACT: 0.127um MIN. GOLD ON CONTACT AREA OVER 2.00um MIN. NICKEL UNDERPLATE.
 - SOLDERTAIL: 1.27um MIN. MATTE TIN OVER 2.00um MIN. NICKEL UNDERPLATE.
 - 3. PRODUCT SPECIFICATION: PS-151073-0001
 - 4. PACKAGING SPECIFICATION: PK-151073-0001
 - 5. OVERALL (SOLDERTAIL & SOLDERTAB) COPLANARITY 0.08MM MAX. BEFORE REFLOW.
 - 6. CONNECTOR TO BE USED TOGETHER WITH MOLEX NANO SIM CARD TRAY ONLY.
 - △ DIMENSION INCLUSIVE OF BULGE
 - 8. CUSTOMER STENCIL THICKNESS: 0.10 ~ 0.12mm AND STENCIL OPENING: 1:1 MIN , 1:1.5 MAX

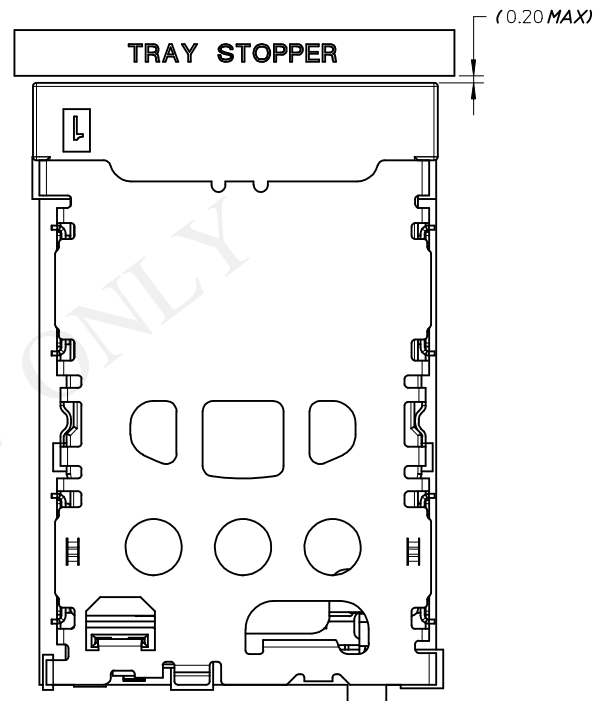
PRELIM. RELEASE EC NO: S2016-0054 DRWNS: SCHEONG 2015/07/07 CHKD: APPR: SCHEONG 2015/07/14 REV	QUALITY SYMBOLS $\nabla = 0$ $\nabla = 6$ $\nabla = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.10 ± --- 1 PLACE ± --- ± --- 0 PLACE ± --- ± --- ANGULAR ± 3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION STYLE MM ONLY DRAWN BY SCHEONG DATE 2015/07/07 CHECKED BY DATE APPROVED BY SCHEONG DATE 2015/07/14 MATERIAL NO. SEE TABLE	SCALE NTS DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE NANO SIM CONNECTOR 1.32MM HEIGHT WITH TRAY AND DETECT PIN molex DOCUMENT NO. SD-151073-0010 SHEET NO. 1 OF 3	
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

9 8 7 6 5 4 3 2 1

CENTRELINES OF TRAY AND CONNECTOR OPENING ARE THE SAME



CONNECTOR WITH TRAY



SYSTEM LEVEL

DESCRIPTION	PART NUMBER
CONNECTOR	151073-0001
NANO SIM CARD TRAY	151073-0030

CARD INSERTION STATE	DETECT SWITCH CIRCUIT STATE	SCHEMATIC
CARD MATED	OPENED	
CARD UNMATED	CLOSED	

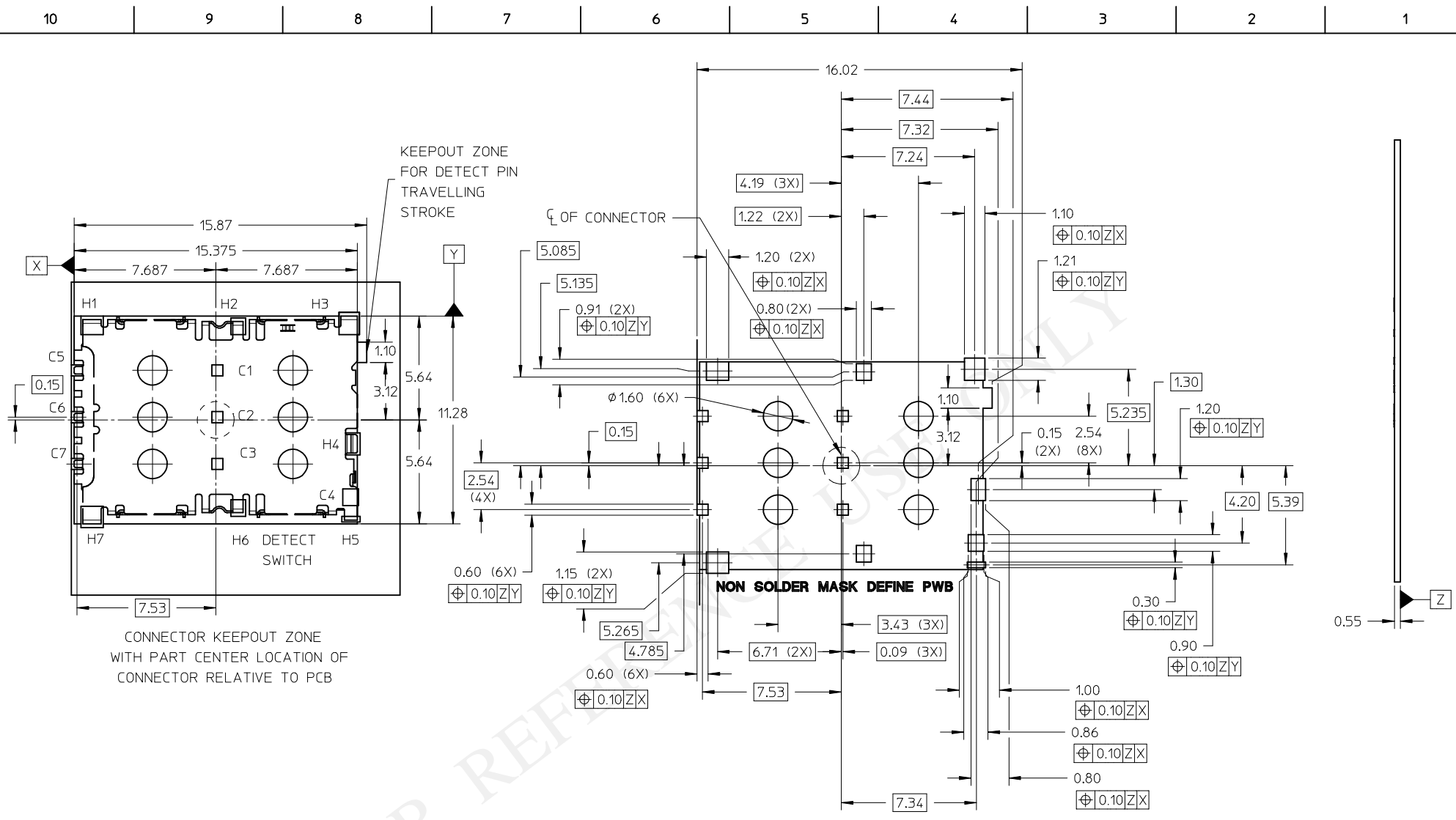
PRELIM. RELEASE	2015/07/07
EC NO: S2016-0054	
DRWNS: SCHEONG	2015/07/14
CHKD:	
APPR: SCHEONG	
REV	DESCRIPTION
1	

QUALITY SYMBOLS
$\nabla = 0$
$\nabla = 0$
$\nabla = 0$

GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm INCH
4 PLACES	\pm --- \pm ---
3 PLACES	\pm --- \pm ---
2 PLACES	± 0.10 \pm ---
1 PLACE	\pm --- \pm ---
0 PLACE	\pm --- \pm ---
ANGULAR $\pm 3^\circ$	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	
MM ONLY	
DRAWN BY	DATE
SCHEONG	2015/07/07
CHECKED BY	DATE
APPROVED BY	DATE
SCHEONG	2015/07/14
MATERIAL NO.	
SEE TABLE	
SIZE	A3

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
NTS	METRIC	
TITLE		
NANO SIM CONNECTOR 1.32MM HEIGHT WITH TRAY AND DETECT PIN		
molex		
MATERIAL NO.	DOCUMENT NO.	SHEET NO.
	SD-151073-0010	2 OF 3



RECOMMENDED PWB LAYOUT
 (NON SOLDER MASK DEFINE PWB)
 PWB TOLERANCE: ±0.05MM

PRELIM. RELEASE EC NO: S2016-0054 DRWN: SCHEONG CHKD: APPR: SCHEONG 2015/07/07 2015/07/14	QUALITY SYMBOLS $\nabla_F = 0$ $\nabla_F = 0$ $\nabla_F = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.10 ± --- 1 PLACE ± --- ± --- 0 PLACE ± --- ± ---	mm INCH	DRAWN BY SCHEONG	DATE 2015/07/07	TITLE NANO SIM CONNECTOR 1.32MM HEIGHT WITH TRAY AND DETECT PIN			
		ANGULAR ± 3 °		CHECKED BY	DATE	molex			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY SCHEONG	DATE 2015/07/14	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-151073-0010	SHEET NO. 3 OF 3	